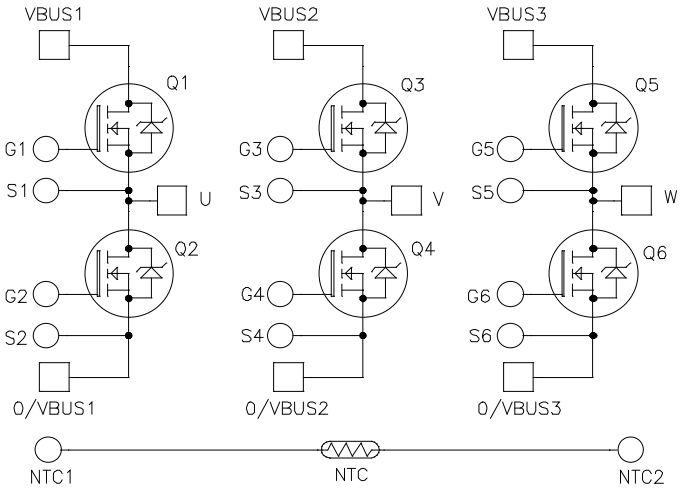
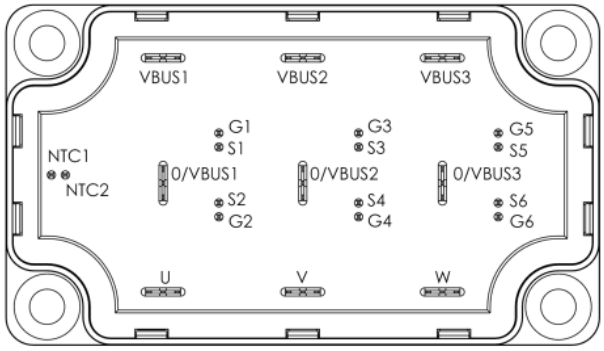
MSCSM120TAM11TPAG

Triple Phase Leg SiC MOSFET Power Module

Product Overview

The MSCSM120TAM11TPAG device is a triple phase leg 1200V, 251A silicon carbide (SiC) power module.





Note: All ratings at T_J = 25 °C, unless otherwise specified.

⚠ CAUTION These devices are sensitive to electrostatic discharge. Proper handling procedures must be followed.

Features

The following are the key features of the MSCSM120TAM11TPAG device:

- SiC Power MOSFET
  - High temperature performance
  - Low $R_{DS(on)}$
- Very low stray inductance
- Kelvin source for easy drive
- Internal thermistor for temperature monitoring
- Aluminum Nitride (AlN) substrate for improved thermal performance

Benefits

The following are the benefits of the MSCSM120TAM11TPAG device:

- High power and efficiency converters and inverters
- Outstanding performance at high frequency operation
- Direct mounting to heatsink (isolated package)
- Low junction-to-case thermal resistance
- Solderable terminals both for power and signal for easy PCB mounting
- Low profile
- RoHS compliant

Applications

The following are the applications of the MSCSM120TAM11TPAG device:

- Uninterruptible power supplies
- Welding converters
- Switched mode power supplies
- EV motor and traction drive

1. Electrical Specifications

This section provides the electrical specifications of the MSCSM120TAM11TPAG device.

1.1 SiC MOSFET Characteristics (Per SiC MOSFET)

The following table lists the absolute maximum ratings of the MSCSM120TAM11TPAG device.

Table 1-1. Absolute Maximum Ratings

Symbol	Parameter		Maximum Ratings	Unit
V_{DSS}	Drain-Source voltage		1200	V
I_D	Continuous drain current	T_C = 25 °C	251[1]	A
		T_C = 80 °C	200[1]	
I_{DM}	Pulsed drain current		500	
V_{GS}	Gate-Source voltage		–10/23	V
$R_{DS(on)}$	Drain-Source ON resistance		10.4	mΩ
P_D	Power dissipation	T_C = 25 °C	1042	W

Note:

1. Specification of SiC MOSFET device but output current must be limited due to the size of power connectors.

The following table lists the electrical characteristics of the MSCSM120TAM11TPAG device.

Table 1-2. Electrical Characteristics

Symbol	Characteristics	Test Conditions		Min.	Typ.	Max.	Unit
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0V V_{DS} = 1200V		—	30	300	µA
$R_{DS(on)}$	Drain-Source on resistance	V_{GS} = 20V I_D = 120A	T_J = 25 °C	—	8.4	10.4	mΩ
			T_J = 175 °C	—	13.4	—	
$V_{GS(th)}$	Gate threshold voltage	V_{GS} = V_{DS} I_D = 9 mA		1.8	2.8	—	V
I_{GSS}	Gate-Source leakage current	V_{GS} = 20V V_{DS} = 0V		—	—	300	nA

The following table lists the dynamic characteristics of the MSCSM120TAM11TPAG device.

Table 1-3. Dynamic Characteristics

Symbol	Characteristics	Test Conditions		Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{GS} = 0V		—	9060	—	pF
C_{oss}	Output capacitance	V_{DS} = 1000V		—	810	—	
C_{rss}	Reverse transfer capacitance	f = 1 MHz		—	75	—	
Q_g	Total gate charge	V_{GS} = –5V/20V		—	696	—	nC
Q_{gs}	Gate-source charge	V_{Bus} = 800V		—	123	—	
Q_{gd}	Gate-drain charge	I_D = 120A		—	150	—	
$T_{d(on)}$	Turn-on delay time	V_{GS} = –5V/20V		—	30	—	ns
T_r	Rise time	V_{Bus} = 600V		—	30	—	
$T_{d(off)}$	Turn-off delay time	I_D = 150A		—	50	—	
T_f	Fall time	R_{GON} = 2.7Ω			25	—	
		R_{GOFF} = 1.6Ω					
E_{on}	Turn-on energy	V_{GS} = –5V/20V	T_J = 150 °C	—	3.6	—	mJ
E_{off}	Turn-off energy	V_{Bus} = 600V		—	2	—	mJ
		I_D = 150A					
		R_{GON} = 2.7Ω					
		R_{GOFF} = 1.6Ω					
R_{Gint}	Internal gate resistance			—	2	—	Ω
R_{thJC}	Junction-to-case thermal resistance			—	—	0.144	°C/W

The following table lists the body diode ratings and characteristics of the MSCSM120TAM11TPAG device.

Table 1-4. Body Diode Ratings and Characteristics

Symbol	Characteristics	Test Conditions	Min.	Typ.	Max.	Unit
V_{SD}	Diode forward voltage	V_{GS} = 0V I_{SD} = 120A	—	4	—	V
		V_{GS} = –5V I_{SD} = 120A	—	4.2	—	
t_{rr}	Reverse recovery time	I_{SD} = 120A	—	90	—	ns
Q_{rr}	Reverse recovery charge	V_{GS} = –5V	—	1650	—	nC
I_{rr}	Reverse recovery current	V_R = 800V di_F/dt = 3000 A/µs	—	40.5	—	A

1.2 Thermal and Package Characteristics

The following table lists the package characteristics of the MSCSM120TAM11TPAG device.

Table 1-5. Thermal and Package Characteristics

Symbol	Characteristic			Min.	Max.	Unit
V_{ISOL}	RMS isolation voltage, any terminal to case t = 1 min, 50 Hz/60 Hz			4000	—	V
T_J	Operating junction temperature range			–40	175	°C
T_{JOP}	Recommended junction temperature under switching conditions			–40	T_{Jmax}–25	
T_{STG}	Storage temperature range			–40	125	
T_C	Operating case temperature			–40	125	
Torque	Mounting torque	To heatsink	M6	3	5	N.m
Wt	Package weight			—	250	g

The following table lists the temperature sensor NTC of the MSCSM120TAM11TPAG device.

Table 1-6. Temperature Sensor NTC

Symbol	Characteristic		Min.	Typ.	Max.	Unit
R_{25}	Resistance at 25°C		—	50	—	kΩ
$\Delta R_{25}/R_{25}$	—	—	—	5	—	%
$B_{25/85}$	T_{25} = 298.15 K	—	—	3952	—	K
ΔB/B	—	T_C = 100 °C	—	4	—	%

$$R_T = \frac{R_{25}}{\exp\left[B_{25/85}\left(\frac{1}{T_{25}} - \frac{1}{T}\right)\right]}$$

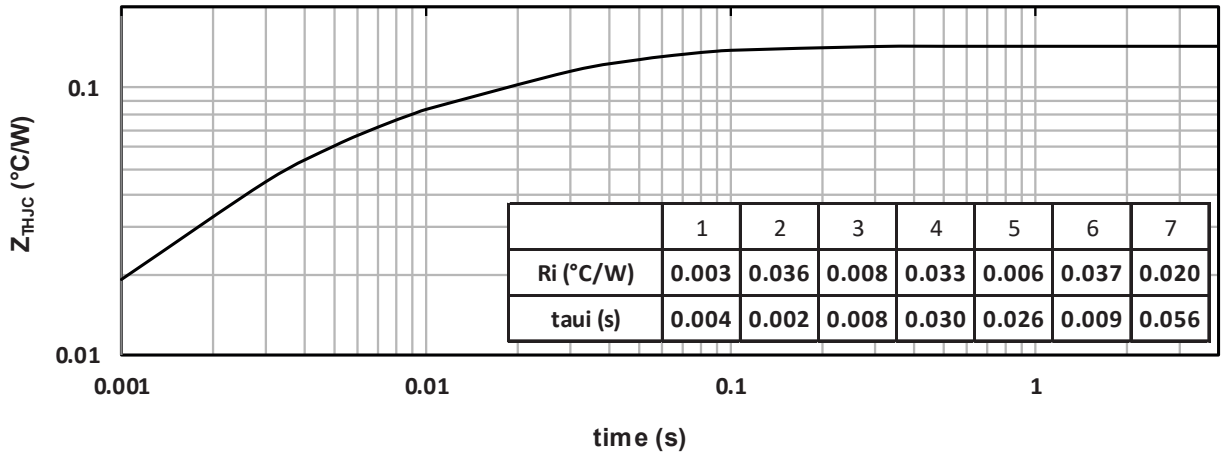
T: Thermistor temperature
R_T: Thermistor value at T

Note: See APT0406—Using NTC Temperature Sensor Integrated into Power Module for more information.

1.3 Typical SiC MOSFET Performance Curve

The following figures show the SiC MOSFET performance curves of the MSCSM120TAM11TPAG device.

Figure 1-1. Maximum Thermal Impedance



	1	2	3	4	5	6	7
Ri (°C/W)	0.003	0.036	0.008	0.033	0.006	0.037	0.020
taui (s)	0.004	0.002	0.008	0.030	0.026	0.009	0.056

Figure 1-2. Output Characteristics, T_J = 25 °C

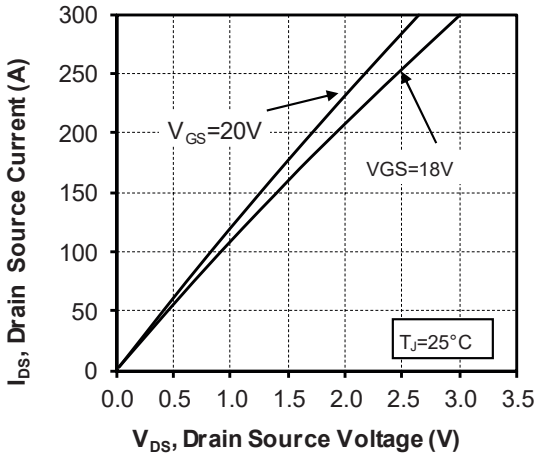


Figure 1-3. Output Characteristics, T_J = 175 °C

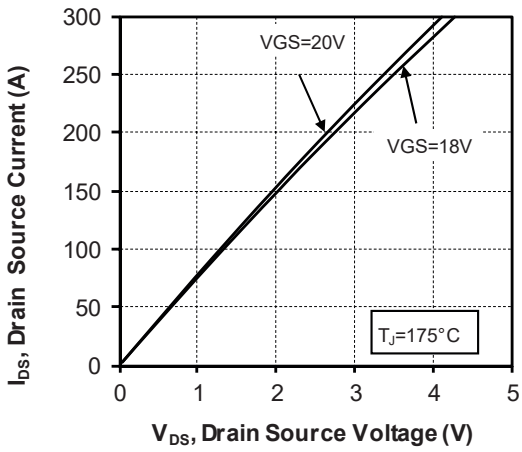


Figure 1-4. Normalized $R_{DS(on)}$ vs. Temperature

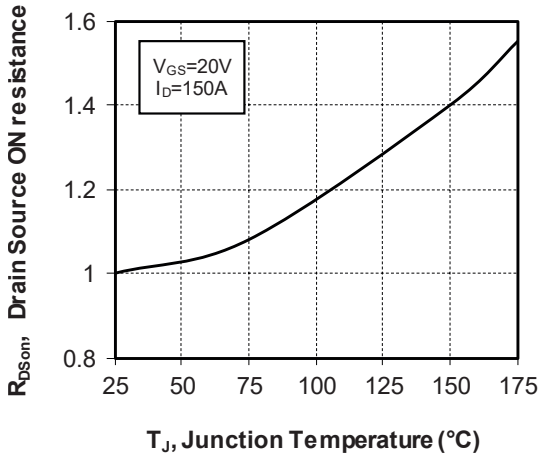


Figure 1-5. Transfer Characteristics

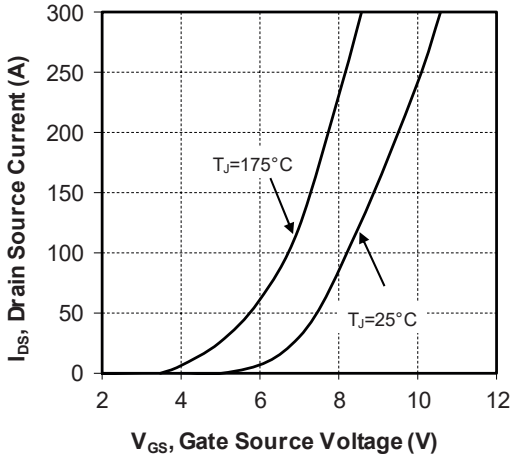


Figure 1-6. Switching Energy vs. Rg

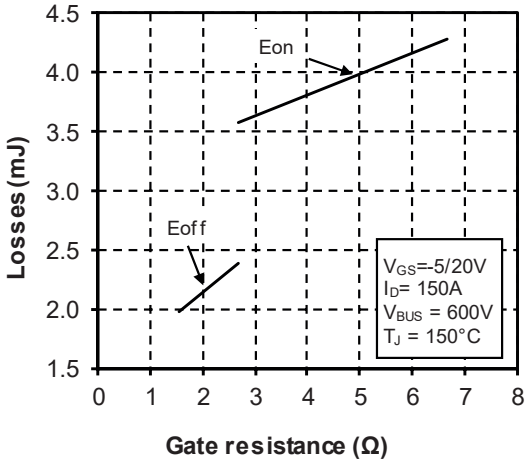


Figure 1-7. Switching Energy vs. Current

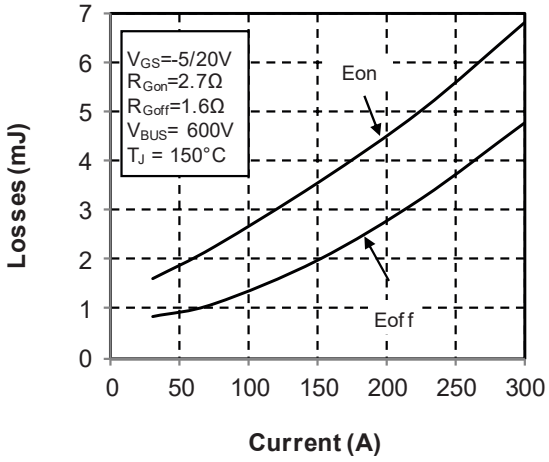


Figure 1-8. Capacitance vs. Drain Source Voltage

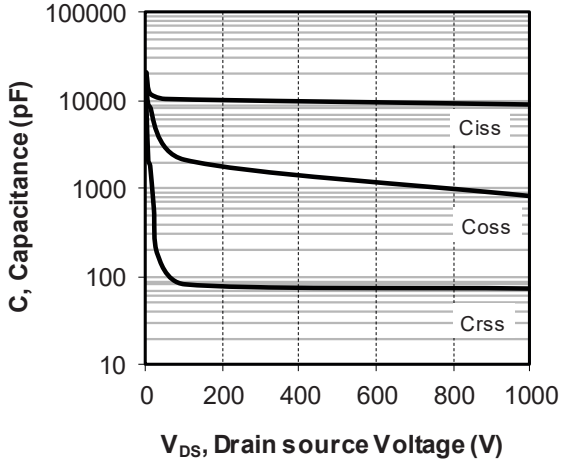


Figure 1-9. Gate Charge vs. Gate Source Voltage

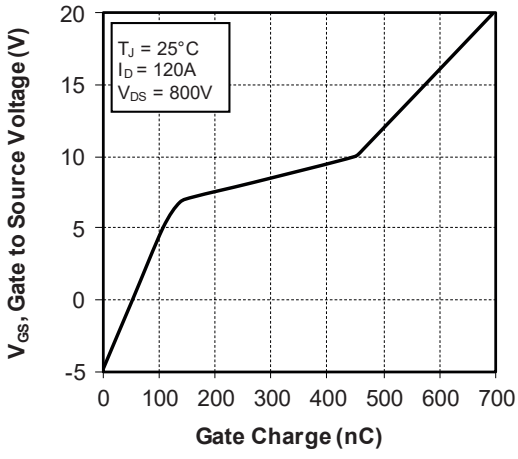


Figure 1-10. Body Diode Characteristics, T_J = 25 °C

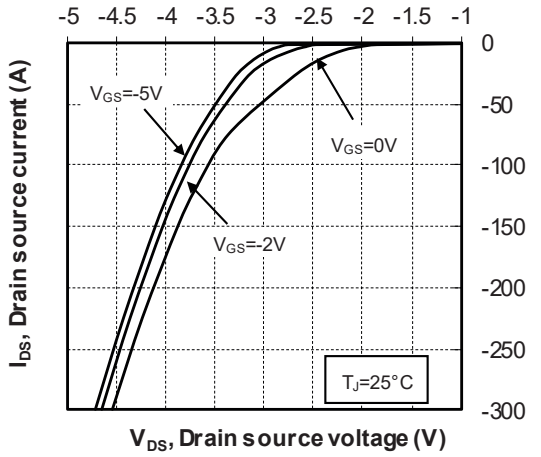


Figure 1-11. 3rd Quadrant Characteristics, T_J = 25 °C

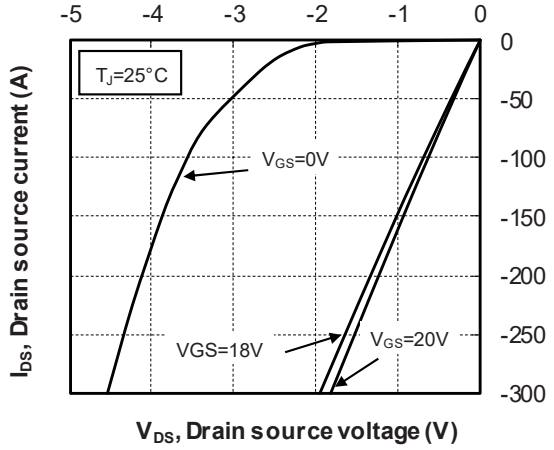


Figure 1-12. Body Diode Characteristics, T_J = 175 °C

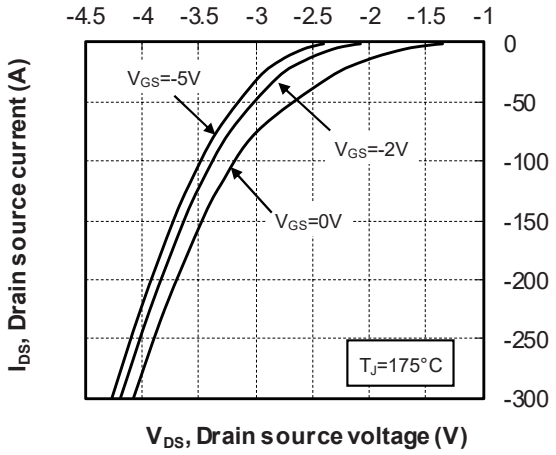


Figure 1-13. 3rd Quadrant Characteristics, T_J = 175 °C

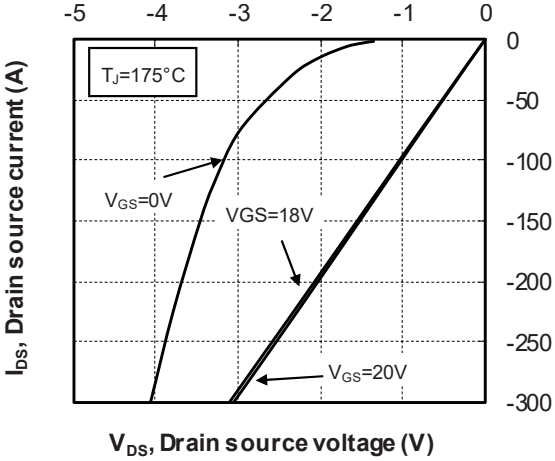
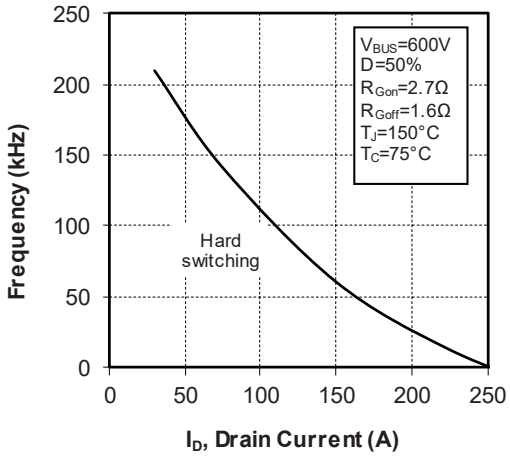


Figure 1-14. Operating Frequency vs. Drain Current



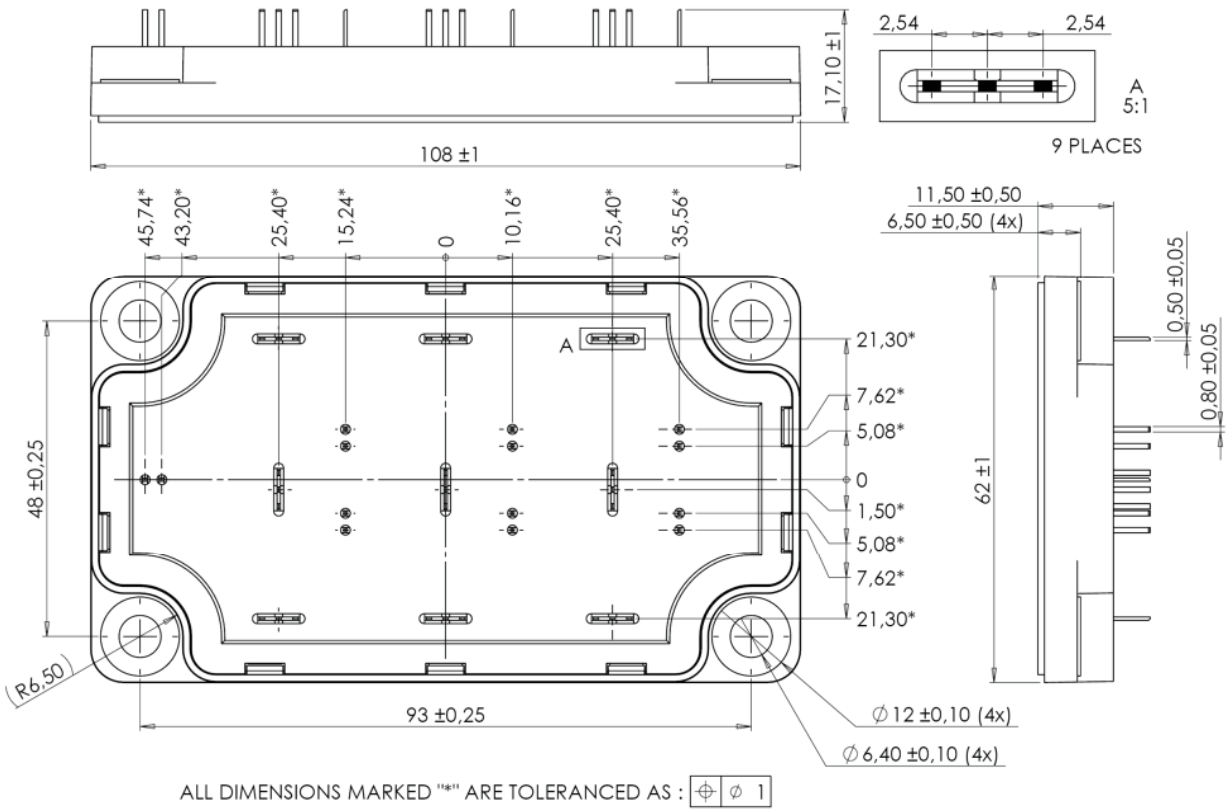
2. Package Specifications

The following section shows the package specification of the MSCSM120TAM11TPAG device.

2.1 Package Outline

The following figure shows the package outline drawing of the MSCSM120TAM11TPAG device. The dimensions in the following figure are in millimeters.

Figure 2-1. Package Outline Drawing



Note: See AN1902—Mounting Instructions for SP6-P (12 mm) Power Modules for more Information.

3. Revision History

Revision	Date	Description
A	06/2022	Initial Revision

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